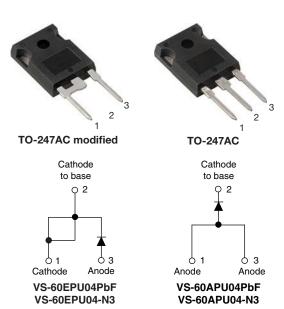
www.vishay.com

Vishay Semiconductors

Ultrafast Soft Recovery Diode, 60 A FRED Pt®



PRODUCT SUMMARY	PRODUCT SUMMARY										
Dookaga	TO-247AC,										
Package	TO-247AC modified (2 pins)										
I _{F(AV)}	60 A										
V_{R}	400 V										
V _F at I _F	1.25 V										
t _{rr} typ.	See Recovery table										
T _J max.	175 °C										
Diode variation	Single die										

FEATURES

- · Ultrafast recovery time
- · Low forward voltage drop
- 175 °C operating junction temperature
- Designed and qualified according t JEDEC-JESD47
- Material categorization:
 For definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

BENEFITS

- · Reduced RFI and EMI
- Higher frequency operation
- Reduced snubbing
- · Reduced parts count

DESCRIPTION/APPLICATIONS

These diodes are optimized to reduce losses and EMI/RFI in high frequency power conditioning systems.

The softness of the recovery eliminates the need for a snubber in most applications. These devices are ideally suited for HF welding, power converters and other applications where switching losses are not significant portion of the total losses.

ABSOLUTE MAXIMUM RATINGS										
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS						
Cathode to anode voltage	V_{R}		400	V						
Continuous forward current	I _{F(AV)}	T _C = 127 °C	60							
Single pulse forward current	I _{FSM}	T _C = 25 °C	600	Α						
Maximum repetitive forward current	I _{FRM}	Square wave, 20 kHz	120							
Operating junction and storage temperatures	T _J , T _{Stg}		- 55 to 175	°C						

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	400	-	-					
Forward voltage		I _F = 60 A	-	1.05	1.25	V				
	V _F	I _F = 60 A, T _J = 175 °C	-	0.87	1.03					
		I _F = 60 A, T _J = 125 °C	-	0.93	1.10					
Reverse leakage current		$V_R = V_R$ rated	-	-	50	μA				
neverse leakage current	I _R	$T_J = 150 ^{\circ}\text{C}, V_R = V_R \text{rated}$	-		2	mA				
Junction capacitance	C _T	V _R = 400 V	-	50	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	3.5	-	nΗ				



www.vishay.com

Vishay Semiconductors

DYNAMIC RECOVERY CHARACTERISTICS (T _C = 25 °C unless otherwise specified)											
PARAMETER	SYMBOL	TEST CO	MIN.	TYP.	MAX.	UNITS					
Reverse recovery time		$I_F = 1 A, dI_F/dt = 20$	-	50	60						
	t _{rr}	T _J = 25 °C		-	85	-	ns A nC				
		T _J = 125 °C		-	145	-					
Pook rocovery ourrent	nt I _{RRM}	T _J = 25 °C	I _F = 60 A dI _F /dt = 200 A/μs	-	8.8	-					
Peak recovery current		T _J = 125 °C	$V_{\rm R} = 200 \text{ V}$	-	15.4	-					
Daylarda raaqyan i aharaa	0	T _J = 25 °C		-	375	-					
Reverse recovery charge	Q _{rr}	T _J = 125 °C		ı	1120	-					

THERMAL - MECHAN	THERMAL - MECHANICAL SPECIFICATIONS											
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS						
Thermal resistance, junction to case	R _{thJC}		-	-	0.70	K/W						
Thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth and greased	-	0.2	ı	IVW						
Weight			-	5.5	-	g						
vveignt			-	0.2	-	oz.						
Mounting torque			1.2 (10)	-	2.4 (20)	N ⋅ m (lbf ⋅ in)						
Madina davia		Case style TO-247AC modified	AC modified 60EPU04									
Marking device		Case style TO-247AC	60APU04									

www.vishay.com

Vishay Semiconductors

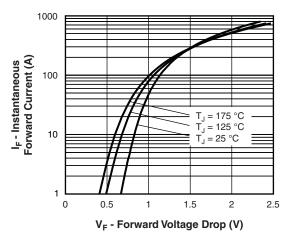


Fig. 1 - Typical Forward Voltage Drop Characteristics

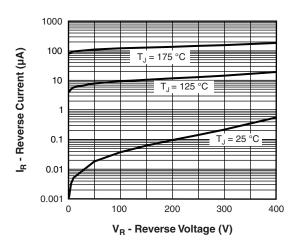


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

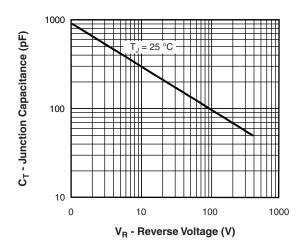


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

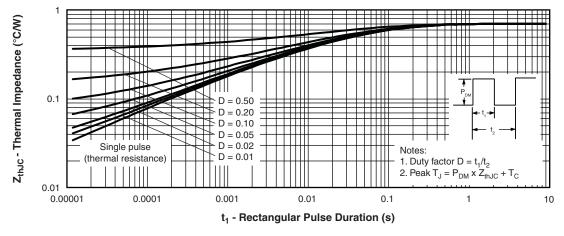


Fig. 4 - Maximum Thermal Impedance ZthJC Characteristics

Vishay Semiconductors

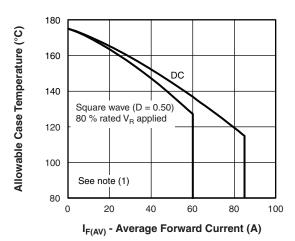


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

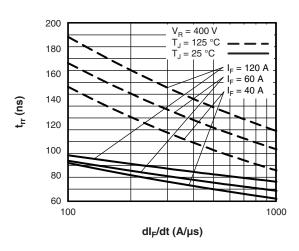


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

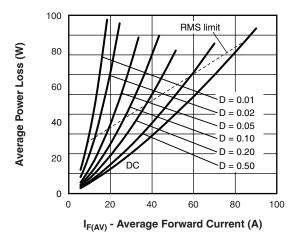


Fig. 6 - Forward Power Loss Characteristics

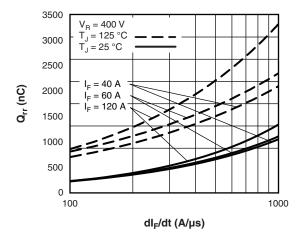


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $^{(1)}$ Formula used: T_C = T_J - (Pd + Pd_{REV}) x R_{thJC}; Pd = Forward power loss = I_{F(AV)} x V_{FM} at (I_{F(AV)}/D) (see fig. 6); Pd_{REV} = Inverse power loss = V_{R1} x I_R (1 - D); I_R at V_{R1} = 80 % rated V_R

www.vishay.com

VS-60EPU04PbF, VS-60EPU04-N3, VS-60APU04PbF, VS-60APU04-N3

Vishay Semiconductors

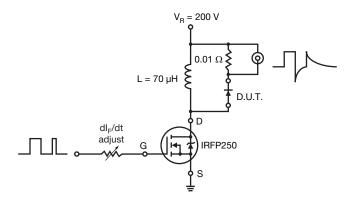
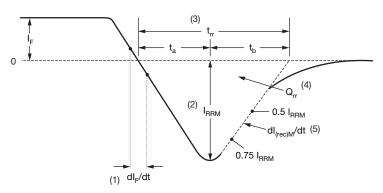


Fig. 9 - Reverse Recovery Parameter Test Circuit



- (1) dl_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (4) $\mathbf{Q}_{\rm rr}$ area under curve defined by $\mathbf{t}_{\rm rr}$ and $\mathbf{I}_{\rm RRM}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

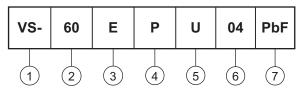
(5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

Fig. 10 - Reverse Recovery Waveform and Definitions

Vishay Semiconductors

ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

2 - Current rating (60 = 60 A)

3 - Circuit configuration:

• E = Single diode

• A = Single diode, 3 pins

4 - Package:

P = TO-247AC (modified)

5 - Type of silicon:

U = Ultrafast recovery

6 - Voltage rating (04 = 400 V)

7 - Environmental digit:

PbF = Lead (Pb)-free and RoHS compliant

-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)										
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION							
VS-60EPU04PbF	25	500	Antistatic plastic tube							
VS-60EPU04-N3	25	500	Antistatic plastic tube							
VS-60APU04PbF	25	500	Antistatic plastic tube							
VS-60APU04-N3	25	500	Antistatic plastic tube							

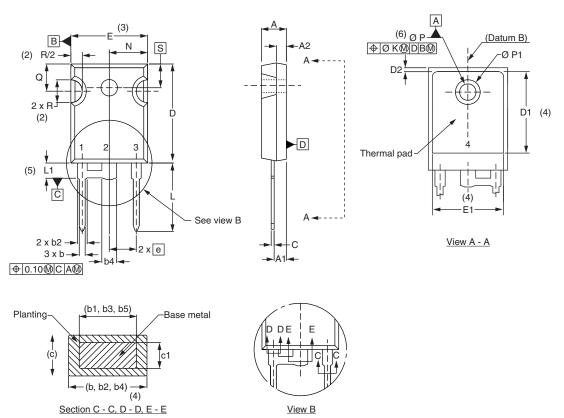
LINKS TO RELATED DOCUMENTS									
Dimensions	TO-247AC modified	www.vishay.com/doc?95541							
Differisions	TO-247AC	www.vishay.com/doc?95542							
	TO-247AC modified PbF	www.vishay.com/doc?95255							
Part marking information	TO-247AC modified -N3	www.vishay.com/doc?95442							
Part marking information	TO-247ACPbF	www.vishay.com/doc?95226							
	TO-247AC-N3	www.vishay.com/doc?95007							



Vishay Semiconductors

TO-247 modified

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES	SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STMBUL	MIN.	MAX.	MIN.	MAX.	NOTES	STWIBUL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209		D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054		E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055		е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053		ØK	0.2	254	0.0)10	
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.33	0.065	0.092		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		N	7.62	BSC	0	.3	
b5	2.59	3.38	0.102	0.133		ØΡ	3.56	3.66	0.14	0.144	
С	0.38	0.89	0.015	0.035		Ø P1	-	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4	S	5.51	BSC	0.217	'BSC	

Notes

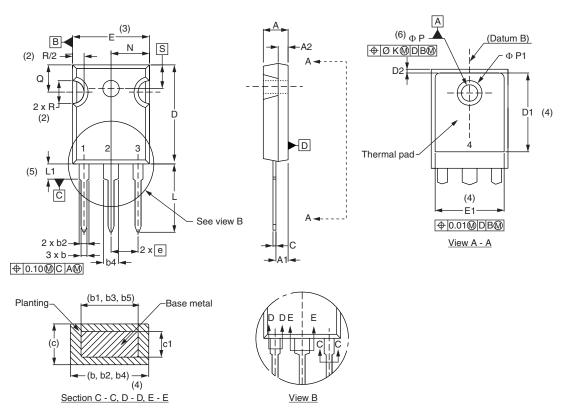
- (1) Dimensioning and tolerance per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



Vishay Semiconductors

TO-247

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INC	HES	NOTES	SYMBOL	MILLIM	IETERS	INC	HES	NOTES
STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES	STIVIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.65	5.31	0.183	0.209		D2	0.51	1.35	0.020	0.053	
A1	2.21	2.59	0.087	0.102		Е	15.29	15.87	0.602	0.625	3
A2	1.17	1.37	0.046	0.054		E1	13.46	-	0.53	-	
b	0.99	1.40	0.039	0.055		е	5.46	BSC	0.215	BSC	
b1	0.99	1.35	0.039	0.053		ØK	0.2	254	0.0)10	
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.33	0.065	0.092		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		N	7.62	BSC	0	.3	
b5	2.59	3.38	0.102	0.133		ØΡ	3.56	3.66	0.14	0.144	
С	0.38	0.89	0.015	0.035		Ø P1	-	7.39	-	0.291	
c1	0.38	0.84	0.015	0.033		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	0.178	0.216	
D1	13.08	-	0.515	-	4	S	5.51	BSC	0.217	'BSC	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

Material Category Policy

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.

Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.

Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.

Revision: 02-Oct-12 Document Number: 91000